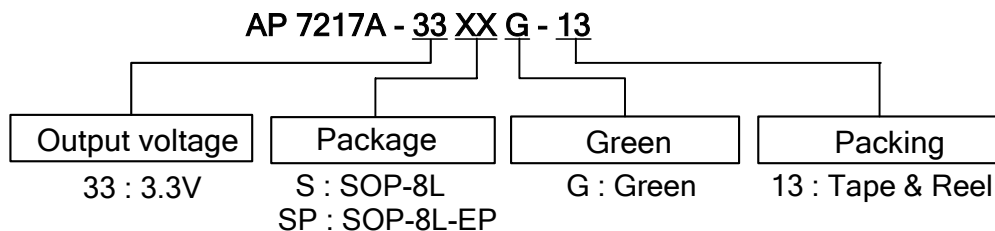


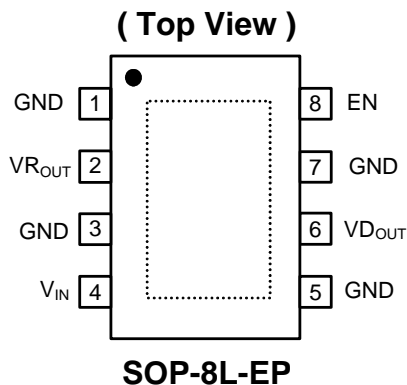
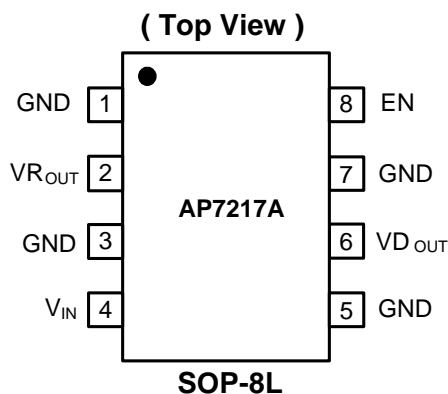
## Ordering Information



Device	Package Code	Packaging (Note 2)	13" Tape and Reel	
			Quantity	Part Number Suffix
AP7217A-33SG-13	S	SOP-8L	2500/Tape & Reel	-13
AP7217A-33SPG-13	SP	SOP-8L-EP	2500/Tape & Reel	-13

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at [http://www.diodes.com/products/lead\\_free.html](http://www.diodes.com/products/lead_free.html).  
 2. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

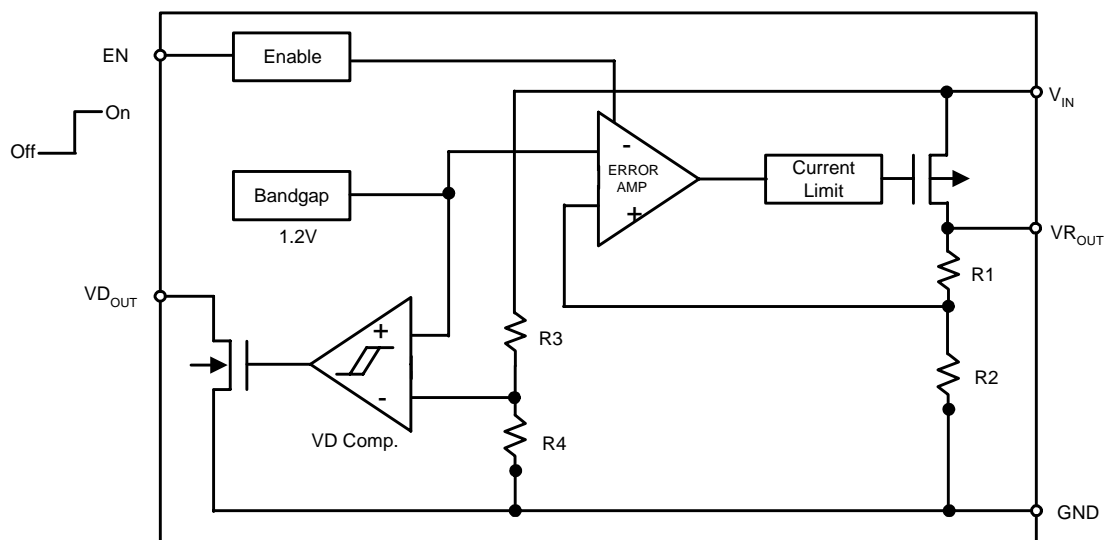
## Pin Assignments



## Pin Descriptions

Pin Name	Pin No.	Description
GND	1, 3, 5, 7	Ground
VR <sub>OUT</sub>	2	Voltage Output
V <sub>IN</sub>	4	Supply Voltage
VD <sub>OUT</sub>	6	V <sub>D</sub> Output (Reset on I/P)
EN	8	Enable (V <sub>R</sub> On/Off)

## Block Diagram



## Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
ESD HBM	Human Body Model ESD Protection		3.5	KV
ESD MM	Machine Model ESD Protection		500	V
$V_{IN}$	Input Voltage		+6	V
$I_{OUT}$	Output Current		$P_D / (V_{IN} - V_O)$	mA
$V_{R\_OUT}$	Output Voltage		GND - 0.3 ~ $V_{IN} + 0.3$	V
$P_D$	Power Dissipation	SOP-8L	1010	mW
		SOP-8L-EP	1650	
$T_J$	Operating Junction Temperature Range		-40 to +125	°C

## Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
$V_{IN}$	Input Voltage	3.3	5.5	V
$I_{OUT}$	Output Current	0	600	mA
$T_A$	Operating Ambient Temperature	-40	85	°C

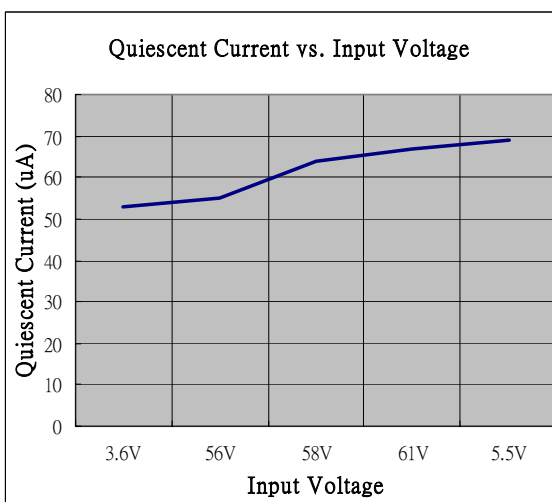
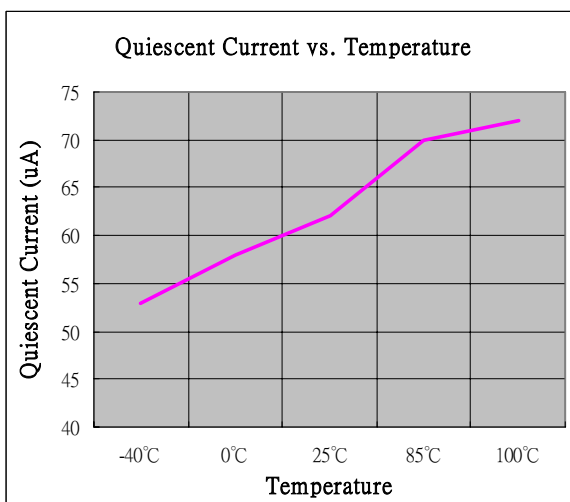
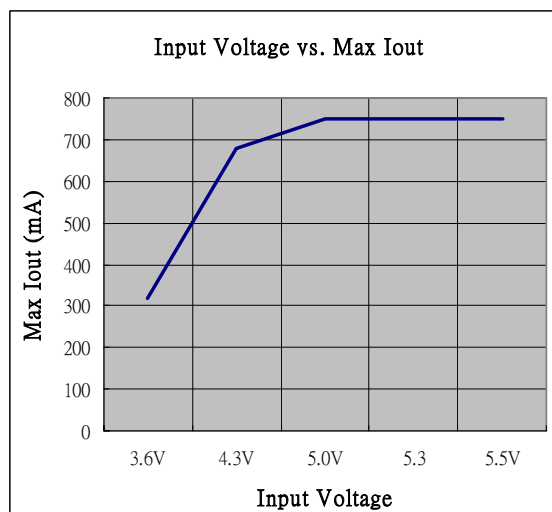
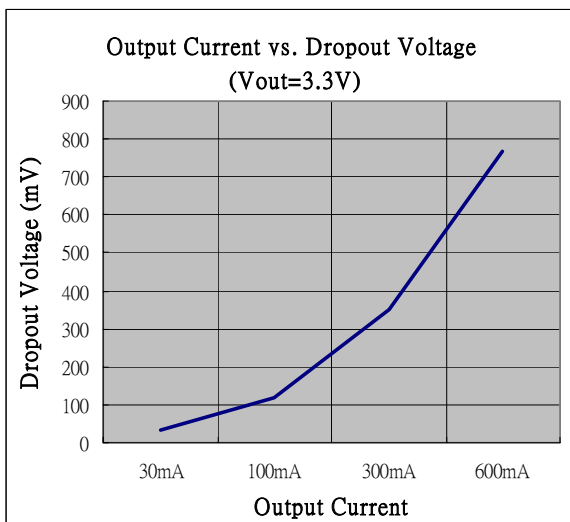
### Electrical Characteristics

(T<sub>A</sub> = 25°C, C<sub>IN</sub> = 1μF, C<sub>OUT</sub> = 1μF, V<sub>EN</sub> = V<sub>IN</sub>, unless otherwise noted)

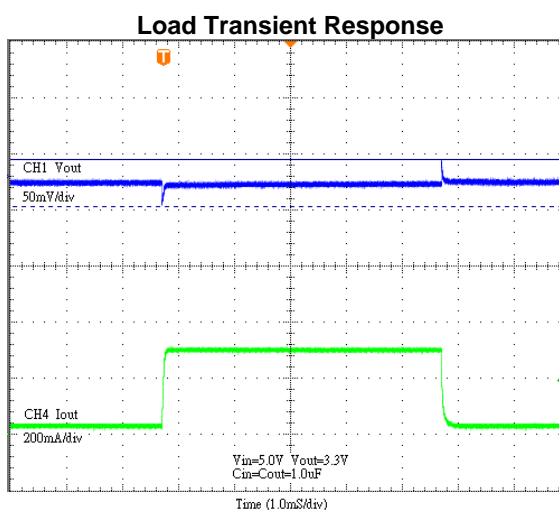
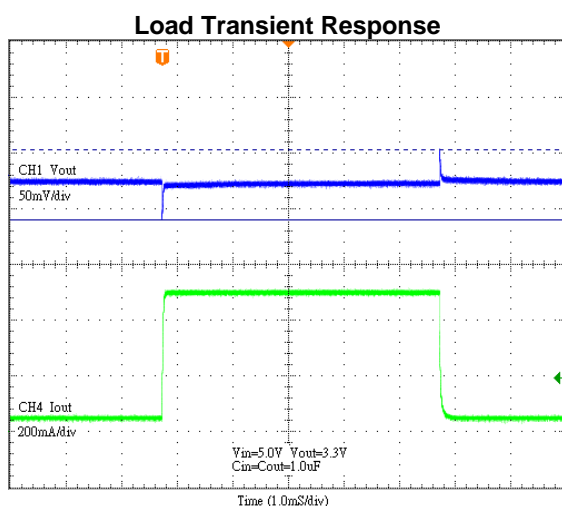
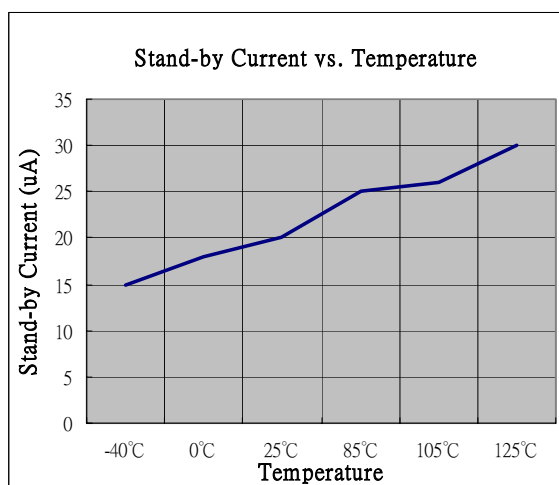
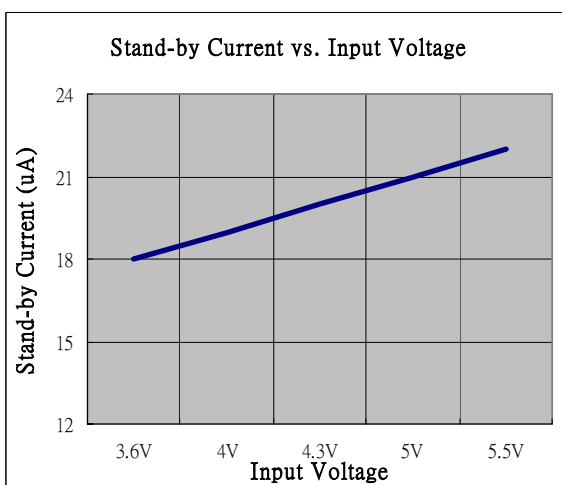
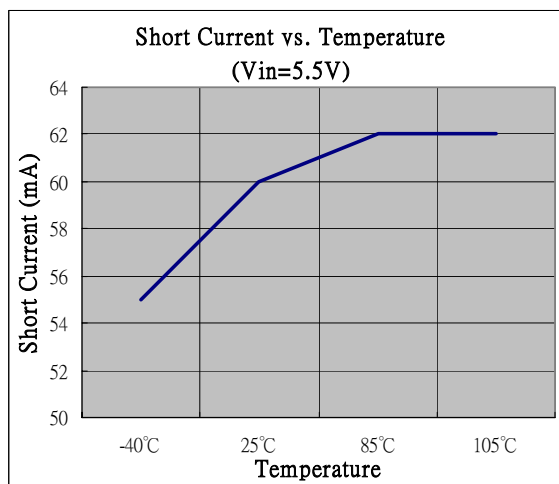
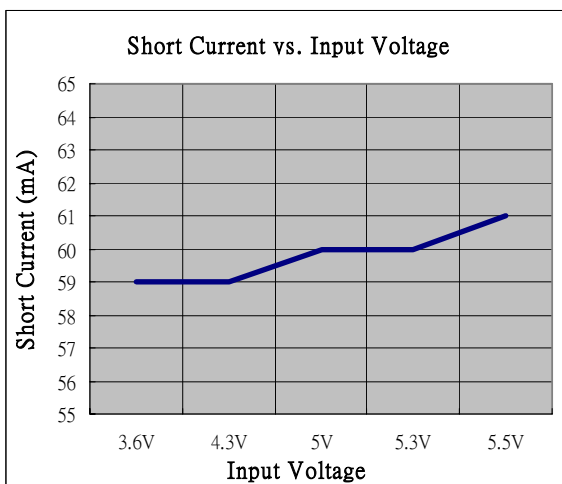
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
I <sub>Q</sub>	Quiescent Current	I <sub>O</sub> = 0mA	-	50	80	μA
I <sub>STB</sub>	Standby Current	V <sub>EN</sub> = Off V <sub>IN</sub> = 5.0V		15	25	μA
V <sub>R</sub> <sub>OUT</sub>	Output Voltage Accuracy	I <sub>O</sub> = 30mA, V <sub>IN</sub> = 5V	3.234	3.300	3.366	V
	V <sub>OUT</sub> Temperature Coefficient	-40°C to 85°C, I <sub>OUT</sub> = 30mA		±100		ppm / °C
V <sub>DROPOUT</sub>	Dropout Voltage	I <sub>OUT</sub> = 300mA		350	400	mV
		I <sub>OUT</sub> = 600mA		800	900	
I <sub>OUT</sub>	Maximum Output Current	V <sub>IN</sub> = 5.3V	600			mA
I <sub>LIMIT</sub>	Current Limit	V <sub>IN</sub> = 5.3V		750		mA
I <sub>short</sub>	Short Circuit Current	V <sub>IN</sub> = 5.3V		50		mA
ΔV <sub>LINE</sub> /ΔV <sub>IN</sub> /V <sub>OUT</sub>	Line Regulation	4.3V ≤ V <sub>IN</sub> ≤ 5.5V; I <sub>OUT</sub> = 30mA		0.01	±0.2	%/V
ΔV <sub>OUT</sub>	Load Regulation	1mA ≤ I <sub>OUT</sub> ≤ 100mA, V <sub>IN</sub> = 5.3V		15	50	mV
PSRR	Power Supply Rejection	V <sub>IN</sub> = 4.3V + 0.5Vp-pAC, F = 1KHz I <sub>OUT</sub> = 50mA		55		dB
V <sub>EH</sub>	EN Input Threshold	Output ON	1.6			V
V <sub>EL</sub>		Output OFF			0.25	V
I <sub>EN</sub>	Enable Pin Current		-0.1		0.1	μA
V <sub>DF</sub>	Detect fall voltage		3.23	3.3	3.37	V
V <sub>D</sub> Hysteresis Range	V <sub>Hysteresis</sub>		V <sub>DF</sub> x1.02	V <sub>DF</sub> x1.05	V <sub>DF</sub> x1.08	V
I <sub>VDout</sub>	VD Supply Current	V <sub>Dout</sub> = 0.5V V <sub>IN</sub> = 2.0V 3.0V		20 30		mA
t <sub>RP</sub>	V <sub>DOUT</sub> Delay Time	V <sub>IN</sub> = 1.8V to V <sub>DF</sub> + 1V	180	200	-	mSec
θ <sub>JA</sub>	Thermal Resistance Junction-to-Ambient	SOP-8L (Note 3)		134		°C/W
		SOP-8L-EP (Note 4)		82		
θ <sub>JC</sub>	Thermal Resistance Junction-to-Case	SOP-8L (Note 3)		28		°C/W
		SOP-8L-EP (Note 4)		12		

Notes: 3. Test condition for SOP-8L: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.  
4. Test condition for SOP-8L-EP: Device mounted on 2oz copper, minimum recommended pad layout on top & bottom layer with thermal vias, double sided FR-4 PCB.

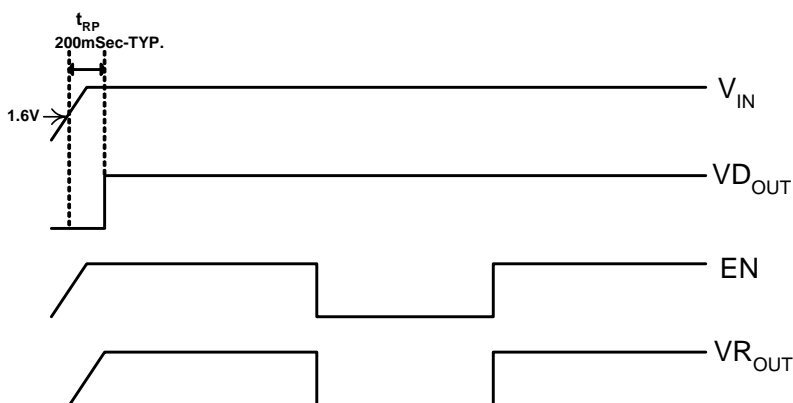
## Typical Performance Characteristics



**Typical Performance Characteristics (Continued)**



### Timing Diagram



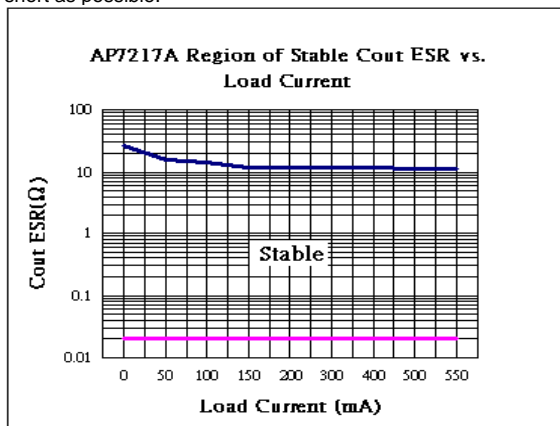
### Application Note

#### Input Capacitor

A 1 $\mu$ F ceramic capacitor is recommended to connect between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. A lower ESR (Equivalent Series Resistance) capacitor allows the use of less capacitance, while higher ESR type requires more capacitance. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both IN and GND.

#### Output Capacitor

The output capacitor is required to stabilize and help the transient response of the LDO. The AP7217A is designed to have excellent transient response for most applications with a small amount of output capacitance. The AP7217 is stable with any small ceramic output capacitors of 1.0 $\mu$ F or higher value, and the temperature coefficients of X7R or X5R type. Additional capacitance helps to reduce undershoot and overshoot during transient. For PCB layout, the output capacitor must be placed as close as possible to OUT and GND pins, and keep the leads as short as possible.



#### ENABLE/SHUTDOWN Operation

The AP7217A is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to IN pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under  $V_{IL}$  and  $V_{IH}$ .

	$VR_{OUT}$	$VD_{OUT}$
EN=0	0V	$\phi$
EN=1	3.3V	$\phi$

#### Thermal Considerations

Thermal Shutdown Protection limits power dissipation in AP7217A. When the operation junction temperature exceeds 150°C, the Over Temperature Protection circuit starts the thermal shutdown function and turns the pass element off. The pass element turn on again after the junction temperature cools by 40°C. For continuous operation, do not exceed absolute maximum operation junction temperature 125°C. The power dissipation definition in device is:

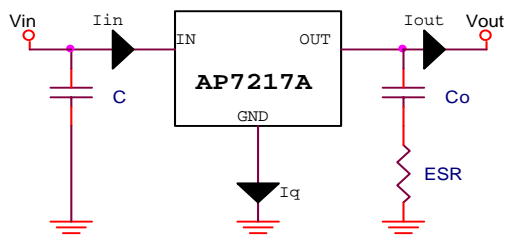
$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_Q$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junction to ambient. The maximum power dissipation can be calculated by following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

Where  $T_{J(MAX)}$  is the maximum operation junction temperature 125°C,  $T_A$  is the ambient temperature and the  $\theta_{JA}$  is the junction to ambient thermal resistance.

### Application Note (Continued)



#### Current Limit Protection

When output current at OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to approximately 750mA to prevent over-current and to protect the regulator from damage due to overheating.

#### Short circuit protection

When  $V_{R_{OUT}}$  pin is shorted to GND or  $V_{R_{OUT}}$  voltage is less than 200mV, short circuit protection will be triggered and clamp the output current to approximately 50mA.

#### $VD_{OUT}$ (reset output)

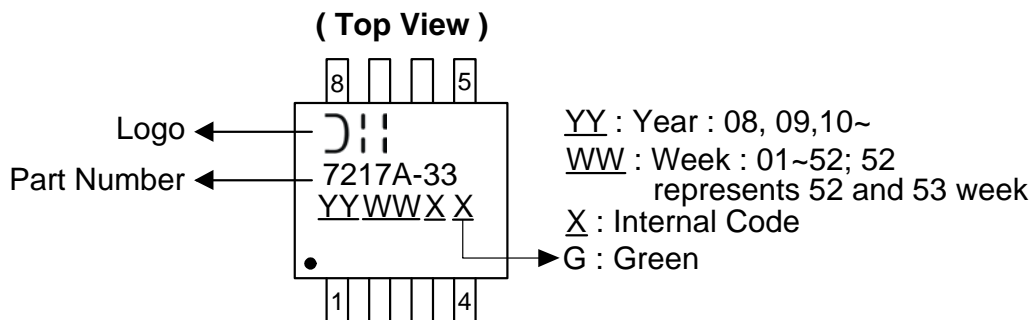
---Open-Drain Active-Low reset output---

In general,  $VD_{OUT}$  is pulled up by a resistor (100Kohm) to  $V_{IN}$ . The AP7217A microprocess (uP) supervisory circuitry asserts a guaranteed logic-low reset during power-up and power-down. Reset is asserted asserts when  $V_{IN}$  is below the reset threshold and remain asserted for at least  $t_{RP}$  after  $V_{IN}$  rises above the reset threshold.

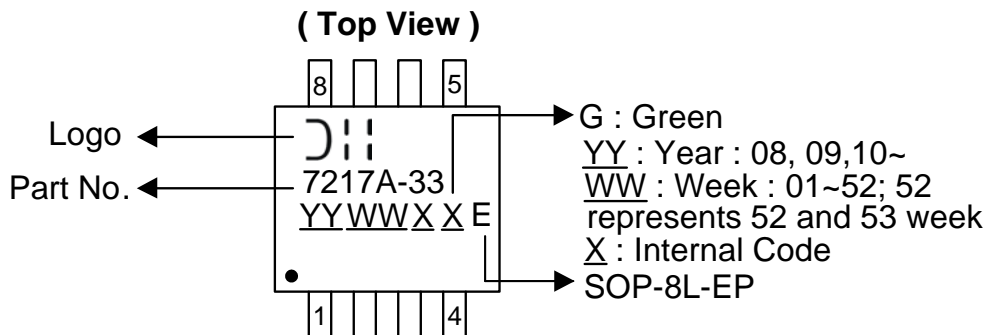
As long as  $V_{IN}$  is lower than the reset threshold,  $VD_{OUT}$  remains at logic "0". When  $V_{IN}$  become higher than  $V_{TH}$ , a logic "1" is asserted after a time delay defined by  $t_{RP}$ .

### Marking Information

#### (1) SOP-8L

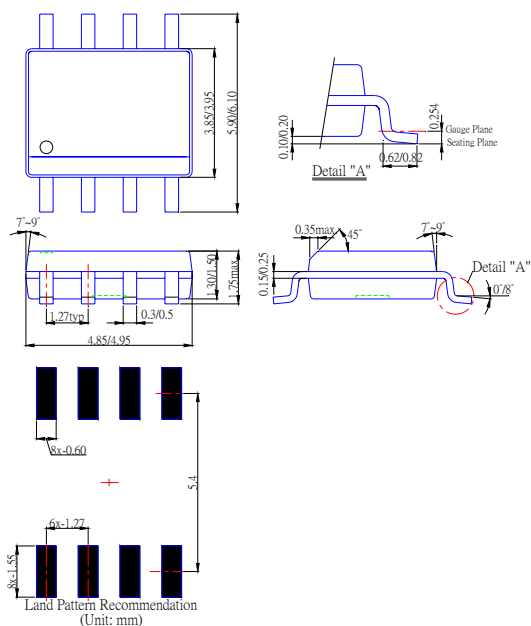


#### (2) SOP-8L-EP

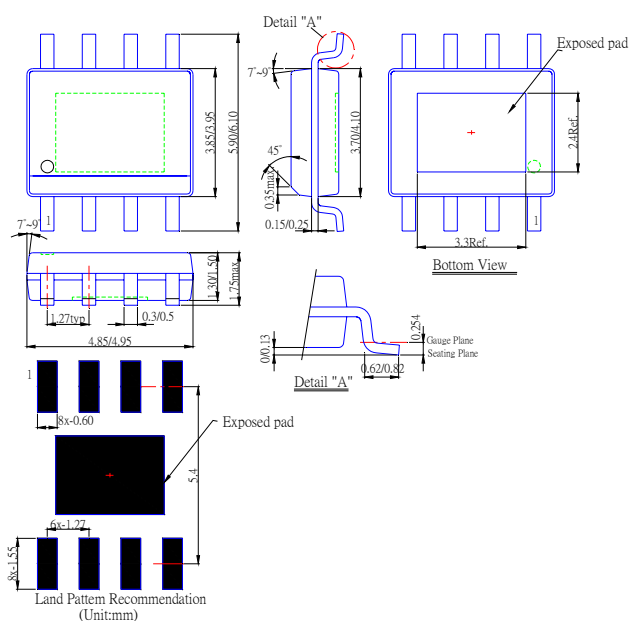


**Package Information** (All Dimensions in mm)

**(1) Package Type: SOP-8L**



**(2) Package Type: SOP-8L-EP**





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